

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (original): An optical integrated circuit package, comprising:
an integrated circuit having a first surface and a second surface, the first surface having a first set of light emitting or sensing devices and a plurality of bond pads;
a conductive bump formed on each of the respective bond pads; and
a clear molding material that encapsulates the integrated circuit and a portion of each conductive bump such that each conductive bump is partially exposed through the clear molding material, whereby light can pass through the clear molding material and reach the first set of light emitting or sensing devices.
2. (original): An optical integrated circuit package as recited in claim 1, further comprising:
a metal pad that is attached to the second surface of the integrated circuit wherein the metal pad is partially encapsulated by the clear molding material.
3. (original): An optical integrated circuit package as recited in claim 2, wherein the metal pad has locking ledges extending from the peripheral edges of the metal pad, whereby the locking ledges serve to lock the metal pad within the clear molding material.
4. (original): An optical integrated circuit package, comprising:
an integrated circuit having a first surface and a second surface, the first surface having a first and second set of light emitting or sensing devices and a plurality of bond pads;
a conductive bump formed on each of the respective bond pads; and
a clear molding material that encapsulates the integrated circuit and a portion of each conductive bump such that each conductive bump is partially exposed through the clear molding material, whereby light can pass through the clear molding material and reach the first set of light emitting or sensing devices.

5. (original): An optical integrated circuit package as recited in claim 4, further comprising:
a metal pad that is attached to the second surface of the integrated circuit wherein the metal pad is partially encapsulated by the clear molding material.
6. (original): An optical integrated circuit package as recited in claim 5, wherein the metal pad has locking ledges extending from the peripheral edges of the metal pad, whereby the locking ledges serve to lock the metal pad within the clear molding material.
7. (previously presented): An optical integrated circuit package as recited in claim 1, wherein the conductive bumps are solder bumps.
8. (previously presented): An optical integrated circuit package as recited in claim 1, wherein the first set of light emitting or sensing devices are located between the plurality of bond pads.
9. (previously presented): An optical integrated circuit package as recited in claim 1, wherein an exposed portion of the conductive bumps is substantially coplanar with an exposed surface of the clear molding.
10. (previously presented): An optical integrated circuit package as recited in claim 2, wherein the metal pad is partially exposed through the clear molding material.
11. (previously presented): An optical integrated circuit package as recited in claim 10, wherein an exposed portion of the metal pad is substantially coplanar with an exposed surface of the clear molding.
12. (previously presented): An optical integrated circuit package as recited in claim 4, wherein the conductive bumps are solder bumps.
13. (previously presented): An optical integrated circuit package as recited in claim 4, wherein the first and second set of light emitting or sensing devices are located between the plurality of bond pads.

14. (previously presented): An optical integrated circuit package as recited in claim 4, wherein an exposed portion of the conductive bumps is substantially coplanar with an exposed surface of the clear molding.

15. (previously presented): An optical integrated circuit package as recited in claim 5, wherein the metal pad is partially exposed through the clear molding material.

16. (previously presented): An optical integrated circuit package as recited in claim 15, wherein an exposed portion of the metal pad is substantially coplanar with an exposed surface of the clear molding.